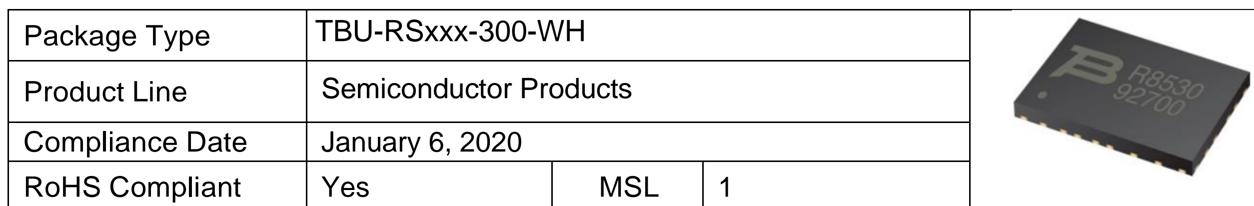
MATERIAL DECLARATION SHEET



Package Type	TBU-RSxxx-300-WH		
Product Line	Semiconductor Products		
Compliance Date	January 6, 2020		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Chip	Silicon	0.0112	Silicon	7440-21-3	100	10.832	10.832
2	Leadframe	Copper Alloy	0.04	Copper	7440-50-8	96	37.1376	38.685
				Iron	7439-89-6	2.2	0.8511	
				Zinc	7440-66-6	0.1	0.0387	
				Phosphorus	7723-14-0	0.075	0.0290	
				Lead	7439-92-1	0.001	0.0004	
				Silver (Plating)	7440-22-4	1.624	0.6282	
3	Die Attach	Conductive Film	0.0012	Epoxy Resin	Trade Secret	5.5	0.0638	1.160
				Polymeric Compound	Trade Secret	0.55	0.0064	
				Functionalised Ester	Trade Secret	0.55	0.0064	
				Silver	7440-22-4	93.4	1.0834	
4	Bond wires	Gold	0.0005	Gold	7440-57-5	99.99	0.48395	0.484
				Non-Au element	Trade Secret	0.01	0.00005	
5	Encapsulation	Epoxy Resin	0.047	Silica Fused	60676-86-0	90.45	41.113	45.454
				Epoxy Resin	Trade Secret	6	2.727	
				Phenol Resin	Trade Secret	3	1.364	
				Carbon Black	1333-86-4	0.55	0.250	
6	Terminal Finish	Tin	0.0035	Tin	7440-31-5	100	3.385	3.385
		Total Weight	0.1034					

This Document was updated on: Sept 22, 2022

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.

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